

54AC16652, 74AC16652 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCAS242A – MARCH 1990 – REVISED APRIL 1996

- **Members of the Texas Instruments Widebus™ Family**
- **Independent Registers and Enables for A and B Buses**
- **Multiplexed Real-Time and Stored Data**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- **EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

description

The 'AC16652 are 16-bit bus transceivers that consist of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. They can be used as two 8-bit transceivers or one 16-bit transceiver.

Complementary output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'AC16652.

54AC16652 . . . WD PACKAGE
74AC16652 . . . DL PACKAGE
(TOP VIEW)

1OEAB	1	56	1OEBA
1CLKAB	2	55	1CLKBA
1SAB	3	54	1SBA
GND	4	53	GND
1A1	5	52	1B1
1A2	6	51	1B2
V _{CC}	7	50	V _{CC}
1A3	8	49	1B3
1A4	9	48	1B4
1A5	10	47	1B5
GND	11	46	GND
1A6	12	45	1B6
1A7	13	44	1B7
1A8	14	43	1B8
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V _{CC}	22	35	V _{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
2SAB	26	31	2SBA
2CLKAB	27	30	2CLKBA
2OEAB	28	29	2OEBA



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description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

The 74AC16652 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16652 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16652 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						DATA I/O [†]		OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
L	H	L	L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	L	X	X	Input	Unspecified [‡]	Store A, hold B
H	H	↑	↑	X [‡]	X	Input	Output	Store A in both registers
L	X	L	↑	X	X	Unspecified [‡]	Input	Hold A, store B
L	L	↑	↑	X	X [‡]	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	L	X	H	X	Input	Output	Stored A data to B bus
H	L	L	L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.

[‡] Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered in order to load both registers.

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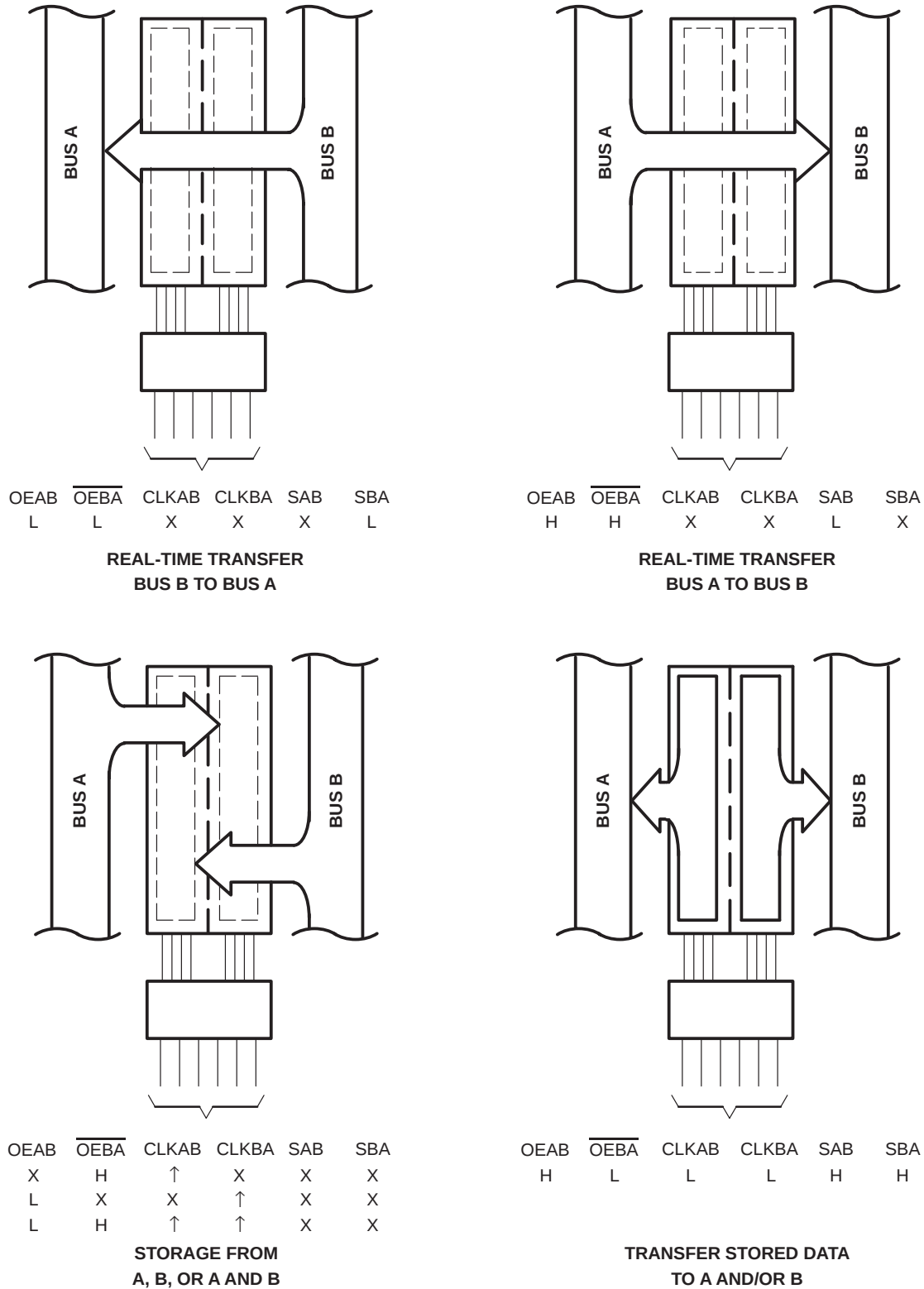


Figure 1. Bus-Management Functions

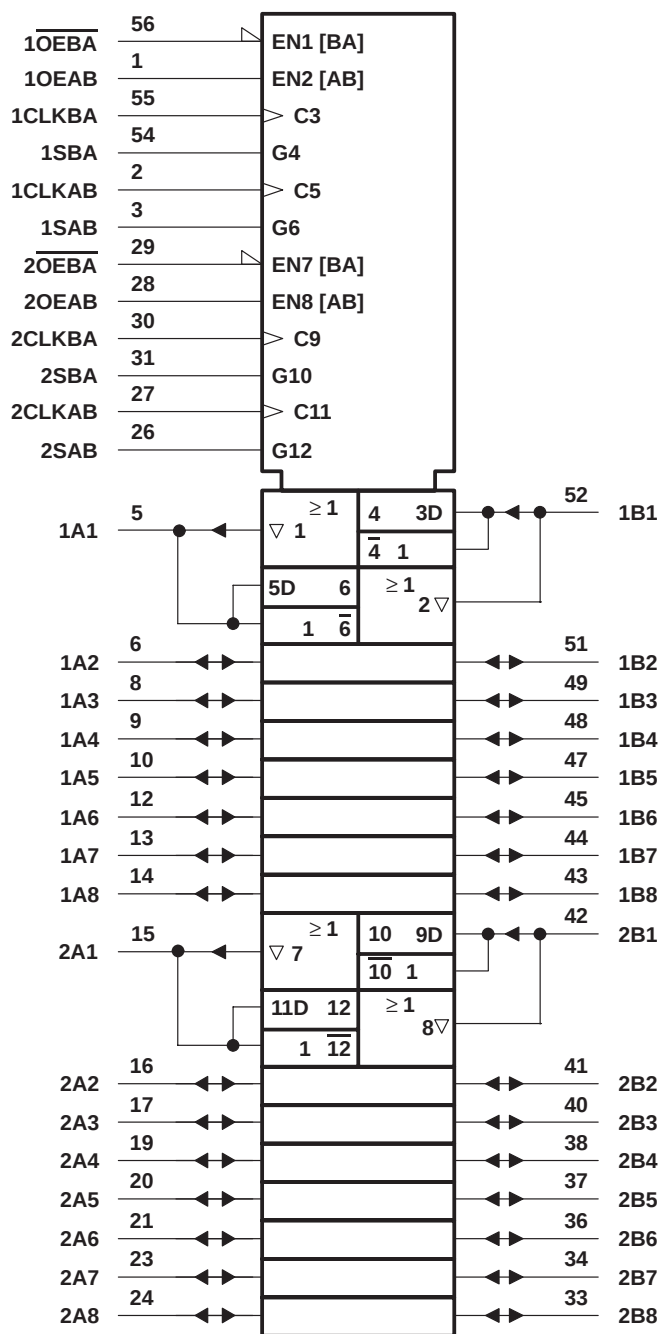
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logic symbol[†]

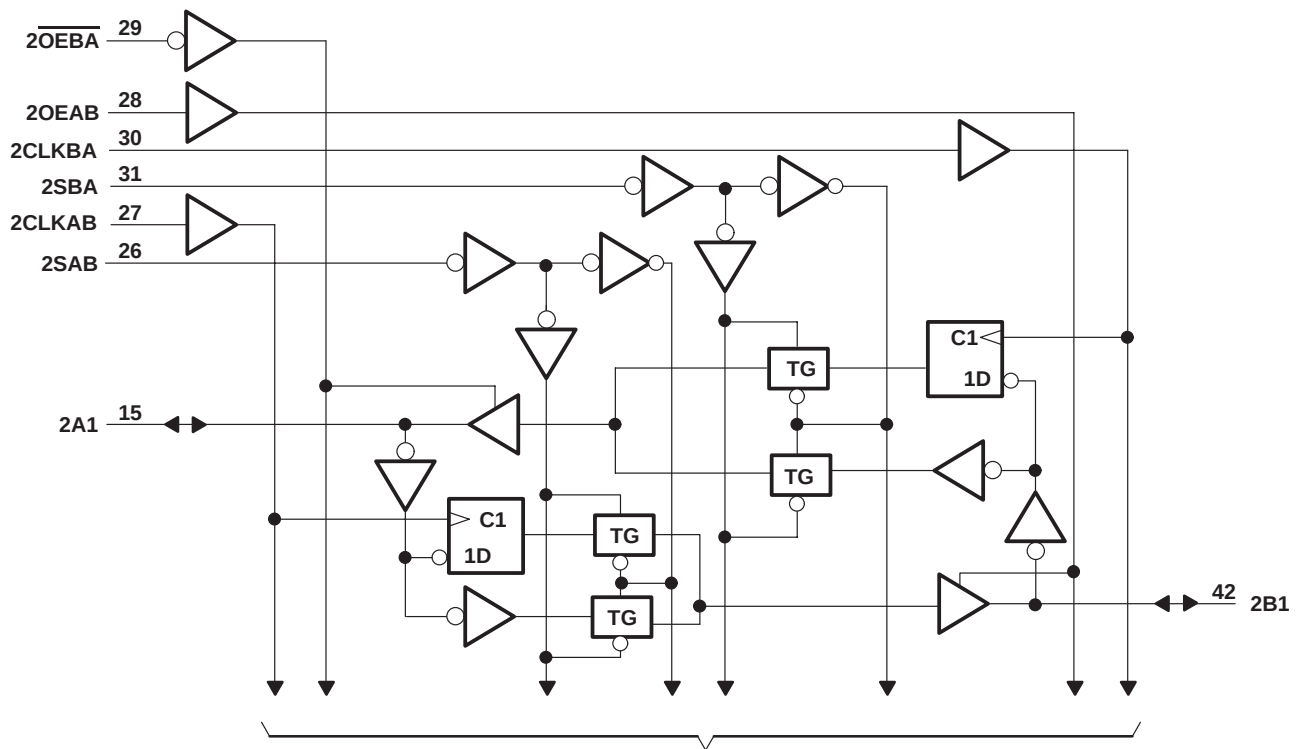
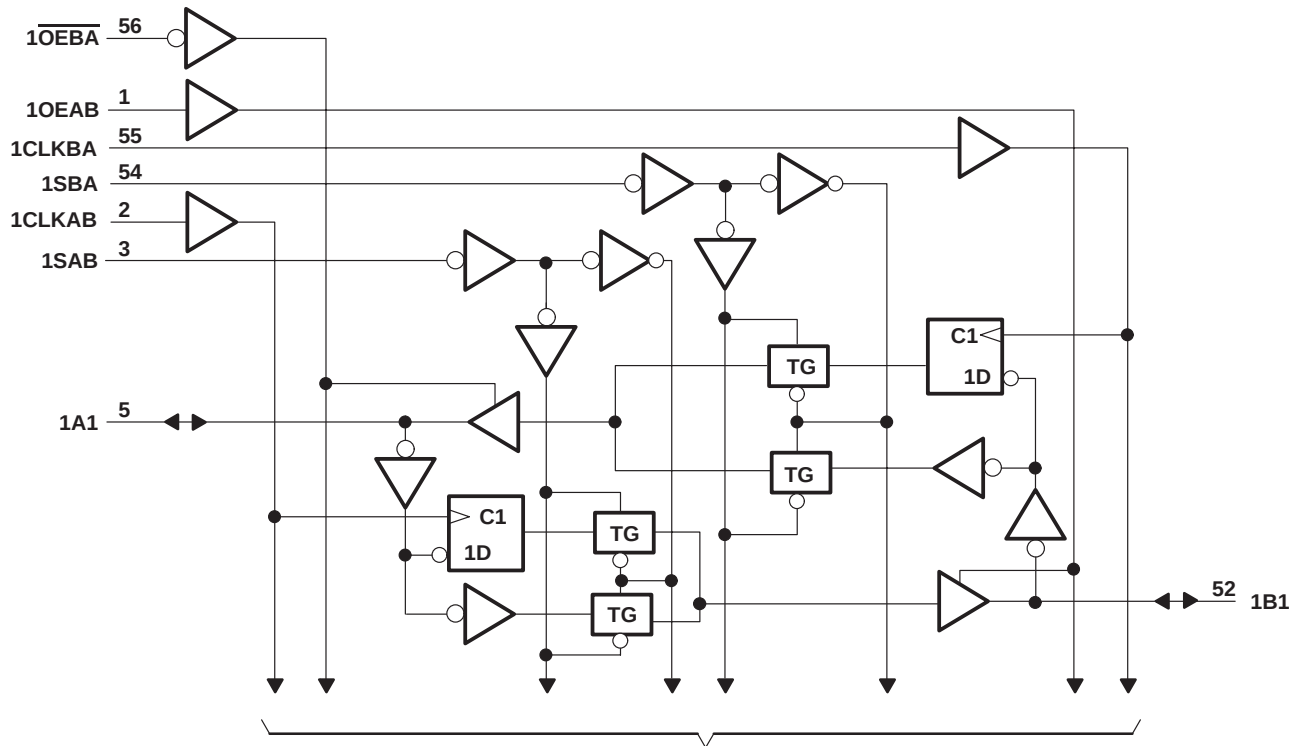


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±400 mA
Maximum package power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16652			74AC16652			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage (see Note 4)		3	5	5.5	3	5	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1			2.1			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 5.5 V	3.85			3.85			
V _{IL}	Low-level input voltage	V _{CC} = 3 V	0.9			0.9			V
		V _{CC} = 4.5 V	1.35			1.35			
		V _{CC} = 5.5 V	1.65			1.65			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
I _{OH}	High-level output current	V _{CC} = 3 V	–4			–4			mA
		V _{CC} = 4.5 V	–24			–24			
		V _{CC} = 5.5 V	–24			–24			
I _{OL}	Low-level output current	V _{CC} = 3 V	12			12			mA
		V _{CC} = 4.5 V	24			24			
		V _{CC} = 5.5 V	24			24			
Δt/Δv	Input transition rise or fall rate		0	10		0	10		ns/V
T _A	Operating free-air temperature		–55	125		–40	85		°C

NOTES: 3. Unused inputs must be held high or low to prevent them from floating.
4. All V_{CC} and GND pins must be connected to the proper voltage power supply.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	T _A = 25°C			54AC16652		74AC16652		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 µA		3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
	I _{OH} = –4 mA		3 V	2.58			2.4		2.48		
			4.5 V	3.94			3.7		3.8		
	I _{OH} = –24 mA		5.5 V	4.94			4.7		4.8		
			5.5 V				3.85				
V _{OL}	I _{OL} = 50 µA		3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
	I _{OL} = 12 mA		3 V			0.36		0.5		0.44	
			4.5 V			0.36		0.5		0.44	
	I _{OL} = 24 mA		5.5 V			0.36		0.5		0.44	
			5.5 V				1.65				
I _I	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	µA
			5.5 V			±0.5		±10		±5	µA
I _{OZ}	A or B ports [‡]	V _O = V _{CC} or GND	5.5 V								µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	5.5 V			8		160		80	µA
C _i	Control inputs	V _I = V _{CC} or GND	5 V			4					pF
C _{iO}	A or B ports	V _O = V _{CC} or GND	5 V			12					pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current.

**timing requirements over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 2)**

		T _A = 25°C		54AC16652		74AC16652		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	0	55	0	55	0	55	MHz
t _w	Pulse duration, CLKAB or CLKBA high or low	9		9		9		ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	7		7		7		ns
t _h	Hold time, A after CLKAB↑ or B after CLKBA↑	0		0		0		ns

**timing requirements over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 2)**

		T _A = 25°C		54AC16652		74AC16652		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	0	95	0	95	0	95	MHz
t _w	Pulse duration, CLKAB or CLKBA high or low	5		5		5		ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5		4.5		4.5		ns
t _h	Hold time, A after CLKAB↑ or B after CLKBA↑	0		0		0		ns

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			54AC16652		74AC16652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			55			55		55		MHz
t_{PLH}	A or B	B or A	3.6	10.4	13.7	3.6	17.1	3.6	15.6	ns
t_{PHL}			4.1	10.9	14.3	4.1	16.3	4.1	15.4	
t_{PLH}	CLKBA or CLKAB	A or B	5.1	13.6	17.3	5.1	21.2	5.1	19.5	ns
t_{PHL}			5.4	13.5	17.2	5.4	19.9	5.4	18.8	
t_{PLH}	SBA or SAB (with A or B high)	A or B	5.8	15.0	18.7	5.8	23.3	5.8	21.4	ns
t_{PHL}			5.4	13.1	16.7	5.4	19.1	5.4	18.1	
t_{PLH}	SBA or SAB (with A or B low)	A or B	4.2	11.8	15.2	4.2	18.9	4.2	17.4	ns
t_{PHL}			5.9	14.4	18.3	5.9	21.7	5.9	20.3	
t_{PZH}	$\overline{\text{OEBA}}$	A	4.2	11.8	15.1	4.2	18.8	4.2	17.2	ns
t_{PZL}			6	16.2	20.6	6	25.3	6	23.5	
t_{PHZ}	$\overline{\text{OEBA}}$	A	4.6	8.1	10	4.6	10.9	4.6	10.6	ns
t_{PLZ}			4.4	7.6	9.6	4.4	10.6	4.4	10.3	
t_{PZH}	OEAB	B	4.1	11.5	14.6	4.1	18.1	4.1	16.6	ns
t_{PZL}			6	16.0	20	6	24.6	6	22.7	
t_{PHZ}	OEAB	B	4.3	7.2	9	4.3	9.7	4.3	9.5	ns
t_{PLZ}			3.9	6.7	8.6	3.9	9.2	3.9	9.1	

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			54AC16652		74AC16652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			95			95		95		MHz
t_{PLH}	A or B	B or A	2.7	6.1	8.8	2.7	10.7	2.7	9.9	ns
t_{PHL}			3	6.3	9.2	3	10.8	3	10.2	
t_{PLH}	CLKBA or CLKAB	A or B	3.9	7.8	10.9	3.9	13.3	3.9	12.2	ns
t_{PHL}			4.2	7.8	11.1	4.2	13.2	4.2	12.3	
t_{PLH}	SBA or SAB (with A or B high)	A or B	4.5	8.8	12.1	4.5	15	4.5	13.8	ns
t_{PHL}			4.1	7.7	11	4.1	12.9	4.1	12.1	
t_{PLH}	SBA or SAB (with A or B low)	A or B	3.1	6.7	9.7	3.1	11.9	3.1	11	ns
t_{PHL}			4.6	8.8	12.2	4.6	14.9	4.6	13.8	
t_{PZH}	$\overline{\text{OEBA}}$	A	3.1	6.7	9.5	3.1	11.6	3.1	10.7	ns
t_{PZL}			4.5	8.3	11.8	4.5	14.4	4.5	13.2	
t_{PHZ}	$\overline{\text{OEBA}}$	A	4.6	6.5	8.3	4.6	9	4.6	8.8	ns
t_{PLZ}			4.1	6.1	8.1	4.1	9.1	4.1	8.7	
t_{PZH}	OEAB	B	3.1	6.6	9.3	3.1	11.3	3.1	10.5	ns
t_{PZL}			4.6	8.2	11.6	4.6	14.1	4.6	13	
t_{PHZ}	OEAB	B	4.2	5.9	7.7	4.2	8.3	4.2	8	ns
t_{PLZ}			3.7	5.5	7.4	3.7	8.3	3.7	7.8	

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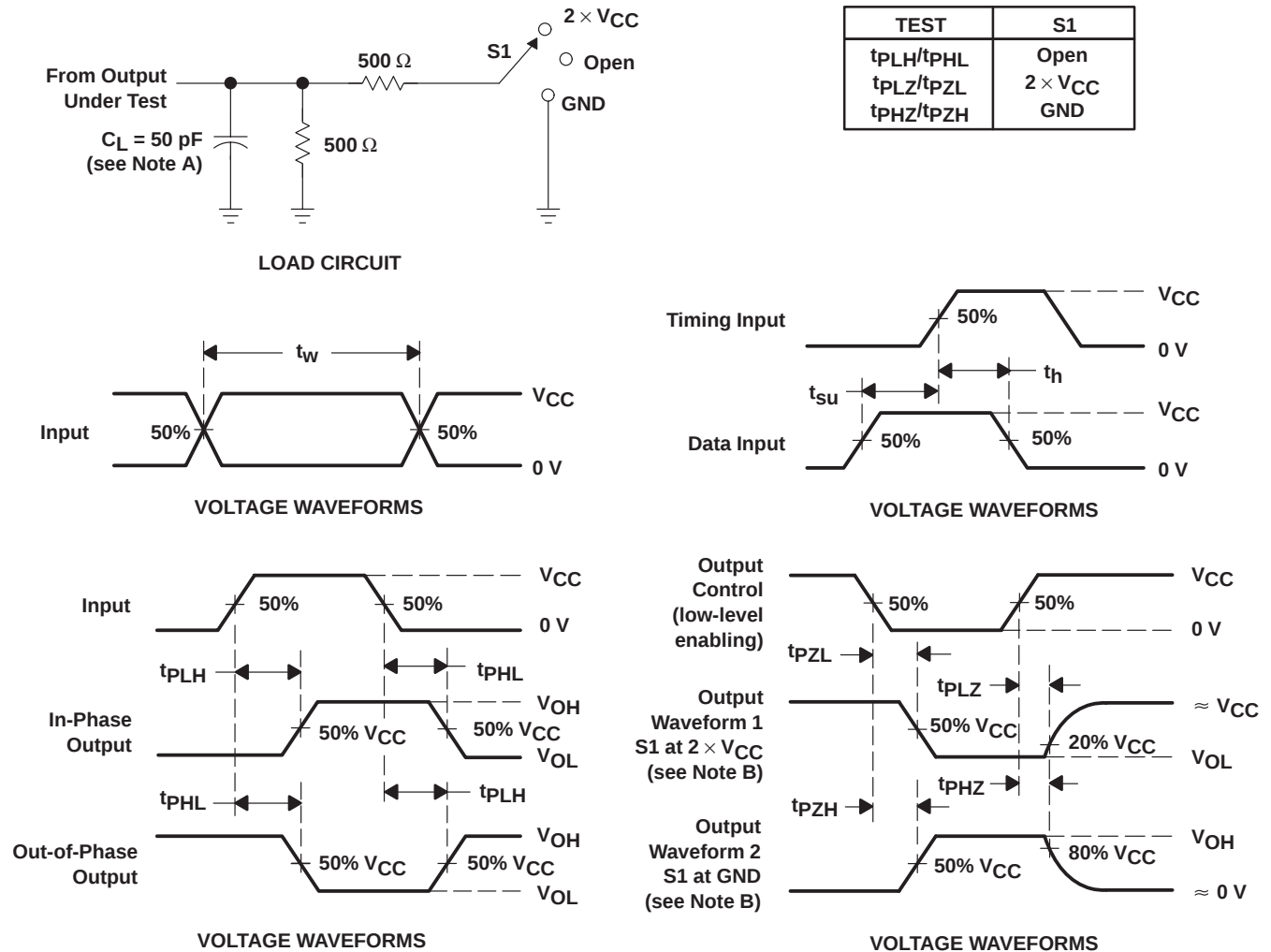
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operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	57	pF
		Outputs disabled	13	

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r = 3\text{ ns}$, $t_f = 3\text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC16652DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16652DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16652DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC16652DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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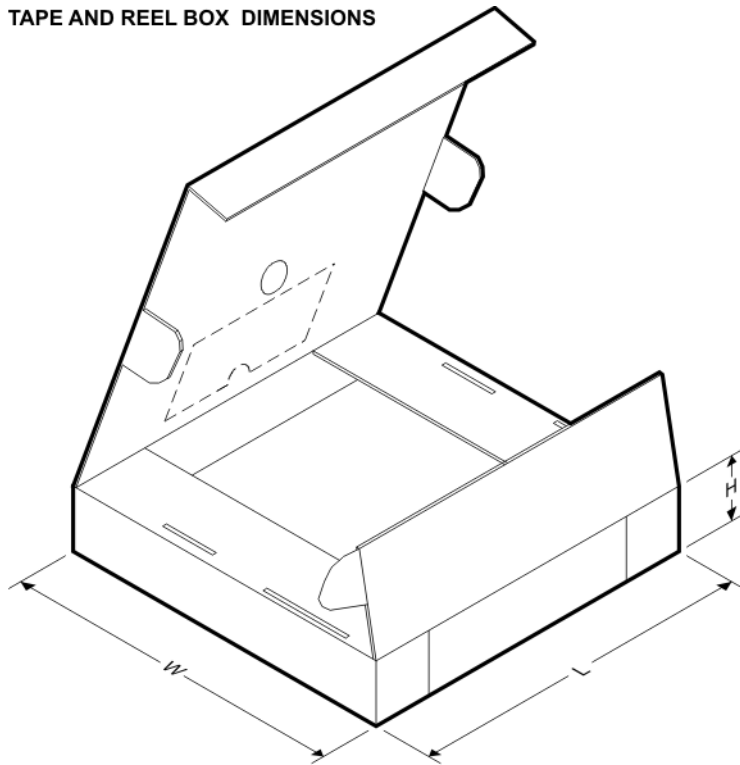
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC16652DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC16652DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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